Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	85	V
RMS Reverse Voltage	$V_{R(RMS)}$	60	V
Forward Current (Single Diode)	I_{FM}	200	mA
Repetitive Peak Forward Current	I_{FRM}	450	mA
Non-Repetitive Peak Forward Surge Current @ t = 1.0μs @ t = 1.0ms @ t = 1.0s	I_{FSM}	4.0 1.0 0.5	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_D	200	mW
Thermal Resistance Junction to Ambient Air (Note 5)	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	85	—	—	V	I_R = 100μA
Forward Voltage	V_F	—	—	0.80 0.90 1.0 1.25	V	I_F = 1.0mA I_F = 10mA I_F = 50mA I_F = 150mA
Leakage Current (Note 6)	I_R	—	—	2.5 30 50	μA	V_R = 70V V_R = 25V, T_J = 150°C V_R = 70V, T_J = 150°C
Total Capacitance (per element)	C_T	—	2	—	pF	V_R = 0, f = 1.0MHz
Capacitance Between Two Data Lines (DL_1 & DL_2, DL_1 & DL_3)	C_{LL}	—	1.6	2.0	pF	V_R = 0, f = 1.0MHz
Capacitance Between Data Line and Ground	C_{LG}	—	2.3	3.0	pF	V_R = 0, f = 1.0MHz
Reverse Recovery Time	t_{rr}	—	—	3.0	μs	I_F = I_R = 10mA, I_{rr} = 0.1 x I_R, R_L = 100Ω

Notes: 5. Device mounted on FR-4 PCB, 1.5 inch x 1.5 inch; 2oz copper with 1" x 1" pad layout.
6. Short duration pulse test used to minimize self-heating effect.

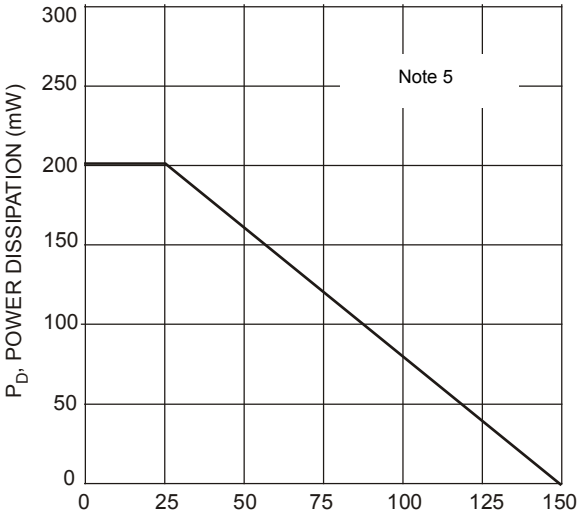

Fig. 1 Power Derating Curve, Total Package

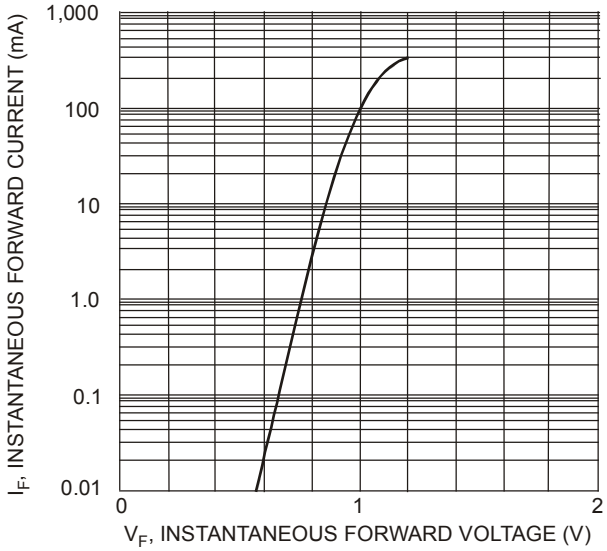

Fig. 2 Typical Forward Characteristics, Per Element

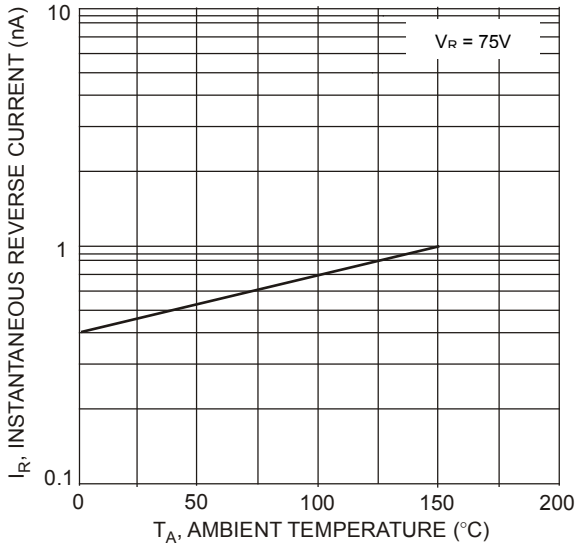

Fig. 3 Typical Reverse Characteristics, Per Element

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

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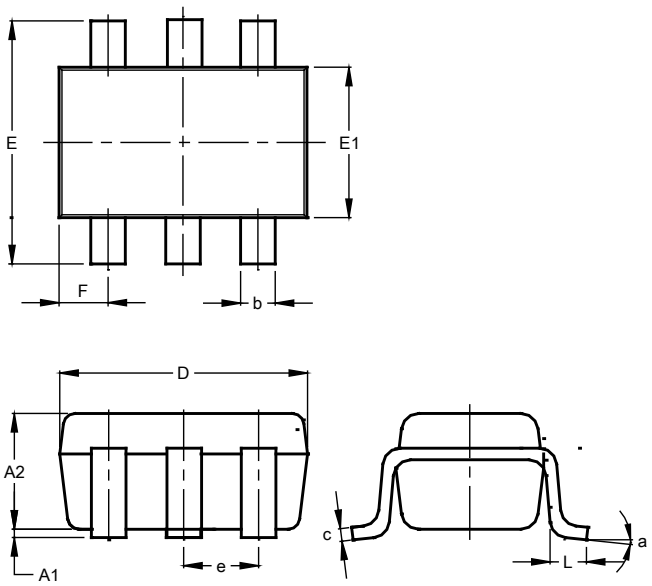

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Dim	**Min**	**Max**	**Typ**
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

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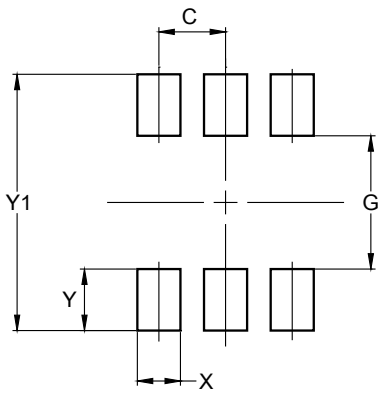

Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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